

02-01-2002

Form PTO 1595



U.S. DEPARTMENT OF COMMERCE  
Patent and Trademark Office

To the Honorable Commiss:

and the attached original documents or copy thereof

1. Name of conveying parties:

101967901

1/18/02

Kevin Song 011602  
Jallepally Ravi 011602  
Shih-Hung Li 011802  
Liang-Yuh Chen 011602

Name and address of receiving parties:

Name: Applied Materials, Inc.  
Internal Address: Legal Affairs Department  
Street Address: P. O. Box 450A  
City: Santa Clara State: CA Zip: 95052

Execution Date: herewith

Additional Names & Addresses attached?  Yes  No

Additional names of conveying Parties attached?  Yes  No

3. Nature of conveyance;

- Assignment  Merger
- Security Agreement  Change of Name
- Other \_\_\_\_\_

Execution Date: See Above

U.S. PTO  
10/053009  
01/18/02

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: herewith

For: Process Conditions and Precursors For Atomic Layer Deposition (ALD) of AL<sub>2</sub>O<sub>3</sub>

A. Patent Application No. \_\_\_\_\_; filed herewith B. Patent No.(s)

Additional Numbers attached?  Yes  No

10/053009

5. Name and address of party to whom correspondence concerning this document should be mailed:

Name: ROBERT W. MULCAHY  
Internal Address: Applied Materials, Inc.  
Legal Affairs Department  
Street Address: P. O. Box 450A  
City: Santa Clara State: CA Zip: 95052

6. Total number of applications and patent involved: 1

7. Total Fee (37 CFR 3.41) \$ 40.00  
 Enclosed  
 Authorized to be charged to deposit account

8. Deposit Account Number: 50-1074  
(Attach duplicate copy of this page if paying by deposit account)

Do Not Use This Space

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and any attached copy is a true copy of the original document.

Robert W. Mulcahy, Reg. No. 25,436

Name of Person Signing

Signature

1-18-02

Date

10. Total number of pages comprising cover sheet, attachments, and document: 5

Mail documents to be recorded with the required cover sheet information to:  
Commissioner of Patents and Trademarks, Box Assignment  
Washington, D.C. 20231

02/01/2002 ANIMED1 00000025 501074 10053009  
01 FC:581 40.00 CH

**ASSIGNMENT FOR APPLICATION FOR PATENT**

WHEREAS:

Names and Addresses of the Inventors:

1)	Kevin Song 2981 Nieman Blvd. #326 San Jose, California 95148	2)	Jallepally Ravi 1655 Betty Ct. Santa Clara, California 95051
3)	Shih-Hung Li 998 #A La Mesa Terrace Sunnyvale, California 84086	4)	Liang-Yuh Chen 1400 Melbourne Street Foster City, California 94404

(hereinafter referred to as Assignors), has invented a certain invention entitled:

**PROCESS CONDITIONS AND PRECURSORS FOR ATOMIC LAYER DEPOSITION (ALD) OF AL<sub>2</sub>O<sub>3</sub>**

for which application for Letters Patent in the United States was filed on \_\_\_\_\_,

under Serial No. \_\_\_\_\_, executed on even date herewith;

WHEREAS, Applied Materials, Inc., a corporation of the State of Delaware, having a place of business at 3050 Bowers Avenue, Santa Clara, California 95054 (hereinafter referred to as Assignee), is desirous of acquiring the entire right, title and interest in and to said application (hereinafter referred to as the Application), and the invention disclosed therein (hereinafter referred to as the Invention), and in and to all embodiments of the Invention, heretofore conceived, made or discovered by said Assignors, and in and to any and all patents, inventor's certificates and other forms of protection (hereinafter referred to as the Patents) thereon granted in any and all countries and groups of countries.

NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sells, assigns, transfers and conveys to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenants and agrees to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use



**ASSIGNMENT FOR APPLICATION FOR PATENT**

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NOW, THEREFORE, in consideration of good and valuable consideration acknowledged by said Assignors to have been received in full from said Assignee:

1. Said Assignors hereby sells, assigns, transfers and conveys to Assignee the full and exclusive right, title and interest (a) in and to said Application and said Invention; (b) in and to all rights to apply for patents on said Invention in any and all countries pursuant to the International Convention for the Protection of Industrial Property or otherwise; (c) in and to any and all Applications filed and any and all Patents granted on said Invention in any and all countries and groups of countries, including each and every Application filed and each and every Patent granted on any application which is a division, substitution, or continuation of said Application; and (d) in and to each and every reissue or extension of any of said Patents.

2. Said Assignors hereby covenants and agrees to cooperate with said Assignee to enable said Assignee to enjoy to the fullest extent the right, title and interest to said Invention herein conveyed in any and all countries and groups of countries. Such cooperation by said Assignors shall include prompt production of pertinent facts and documents, giving testimony, execution of petitions, oaths, specifications, declarations or other papers, and other assistance all to the extent deemed necessary or desirable by said Assignee (a) for perfecting in said Assignee the right, title and interest herein conveyed; (b) for prosecuting any of said applications; (c) for filing and prosecuting substitute, divisional, continuing or additional applications covering said Invention; (d) for filing and prosecuting applications for reissuance of any of said Patents; (e) for interference or other priority proceedings involving said Invention; and (f) for legal proceedings involving said Invention and any application therefor and any Patents granted thereon, including without limitation opposition proceedings, cancellation proceedings, priority contests, public use

proceedings, infringement actions and court actions; provided, however, that the expense incurred by said Assignors in providing such cooperation shall be paid for by said Assignee.

3. The term and covenants of this agreement shall inure to the benefit of said Assignee, its successors, assigns and other legal representatives, and shall be binding upon said Assignors, their respective heirs, legal representatives and assigns.

4. Said Assignors hereby warrants and represents that he has not entered and will not enter into any assignment, contract, or understanding in conflict herewith.

5. Said Assignors hereby authorizes and requests the attorneys of record to insert, where indicated above, the application number and filing date of said application when known.

IN WITNESS WHEREOF, the said Assignors has executed and delivered this instrument to said Assignee on the dates indicated below.

\_\_\_\_\_, 2002

\_\_\_\_\_  
Kevin Song

\_\_\_\_\_, 2002

\_\_\_\_\_  
Jallepally Raji

1/18, 2002

  
\_\_\_\_\_  
Shih-Hung Li

\_\_\_\_\_, 2002

\_\_\_\_\_  
Liang-Yuh Chen